

09/816,055

L Number	Hits	Search Text	DB	Time stamp
-	1838	((438/107) or (257/724)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 15:23
-	1994	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 15:24
-	1195	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 15:25
-	356	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/21 15:26
-	813	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/22 10:32
-	814	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/22 11:07
-	651	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$) and substrate) and mount\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/22 11:09
-	130	((438/107) or (257/724) or (438/127)).CCLS.) and @ad<20000324) and (insulation resin encapsula\$) and substrate) and mount\$) and (mcm or (multi adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/22 11:11